

FLIP CHIP IN LEADED MOLDED PACKAGE AND METHOD OF
MANUFACTURE THEREOF

ABSTRACT OF THE DISCLOSURE

A chip device that includes a leadframe, a die and a mold compound. The backside of the die is metallized and exposed through a window defined within a mold compound that encapsulates the die when it is coupled to the leadframe. Leads on the leadframe are coupled to source and gate terminals on the die while the metallized backside of the die serves as the drain terminals.